

CLEAN VERSION OF REPLACEMENT PARAGRAPH/SECTION/CLAIM

IN THE CLAIM

Please cancel claims 1-4 without prejudice and substitute therefor the following new claim 5 (in "clean form"):

4/ --5. An ultra-thin film package, wherein polymeric film die carrier or polyimide (PI) die carrier is employed, and the leg position for die bonding is made into a recess shape to lower the thickness after bonding, and polymeric film die carrier or PI die carrier is made into a thin film shape by a fabrication technique, and the I/O leg position is made into a recess shape and the die is glued to the polymeric film die carrier or PI die carrier and then changed with a package material, and by means of a dicing step, a single package granule containing dies is cut, wherein polymeric film die carrier or PI die carrier and the die are soldered at one end of a wire, the other end is mounted with a metal pad within the leg position which is recessed on the polymeric die film carrier or PI die carrier, and the electrode of the metal pad is protruded from the back face of the polymeric film die carrier or PI die carrier, a metal plate is provided at the polymeric film die carrier or PI die carrier, corresponding to the back face of the die position, the electrical bonding of the die with polymeric film die carrier or PI die carrier is a die bonding method such that the I/O bump of the die and the metal pad on the leg position of the polymeric film die carrier or PI die carrier are bonded.--